

CLAIMS

1. (Currently amended) A curable dielectric composition comprising polynorbornene, a polymeric diluent which plasticises the composition, a particulate material and a curing agent for the composition wherein the polymeric diluent is an ethylene propylene diene (EPDM) elastomer containing the unsaturated alkylene groups so as to be co-curable with the polynorbornene.

2. (Original) A curable composition according to claim 1, wherein the polymeric components comprise between 5-50% by weight of the composition, more preferably 15-30 wt % and most preferably 20-25 wt %.

3. (Original) A curable composition according to claim 2, wherein of the polymeric components the polynorbornene, is present in an amount of between 70-85% by weight, more preferably between 72-83 wt % and most preferably between 75-80 wt %.

4. (Previously Presented) A curable composition according to claim 1, wherein of the polymeric components the polymeric diluent is present in an amount of between 15-30% by weight, more preferably 17-28 wt % and most preferably 20-25 wt %.

5. (Cancelled) A curable composition according to claim 1, wherein the polymeric diluent is an elastomer.

6. (Cancelled) A curable composition according to claim 1, wherein the polymeric diluent is co-curable with the polynorbornene.

7. (Cancelled) A curable composition according to claim 6, wherein the polymeric diluent includes unsaturated alkylene groups.

8. (Cancelled) A curable composition according to claim 7, wherein the elastomer is an ethylene propylene diene (EPDM).

9. (Original) A curable composition according to claim 8, wherein the diene group of the EPDM is ethylidene norbornene.

10. (Previously Presented) A curable composition according to claim 1, wherein the particulate material is present in the composition in an amount of from 50-95% by weight, more preferably from 70-85 wt % and more preferably about 75-80 wt %.

11. (Previously Presented) A curable composition according to claim 1, wherein the particle size of the particulate material is from 1-250 μm , with from 60-80 μm more preferred and about 70 μm being most preferred.

12. (Previously Presented) A curable composition according to claim 1, wherein the particulate material is titania, silica, fused silica, strontium titanate and/or a mixture thereof.

13. (Previously Presented) A curable composition according to claim 1, wherein the curing agent is a radical initiator.

14. (Previously Presented) A curable composition according to claim 1, wherein the curing agent is typically triggered at between 120-200.degree. C.

15. (Previously Presented) A curable composition according to claim 1, wherein the curing agent is present in an amount of about 5-10% by weight of the polymer.

16. (Previously Presented) A curable composition according to claim 1, wherein the curing agent is a peroxide.

17. (Previously Presented) A curable composition according to claim 1, wherein the composition includes at least one auxiliary agent such as a filler, a fire retardant agent and/or a coupling agent and/or a chain extender.

18. (Original) A curable composition according to claim 17, incorporating magnesium hydroxide, aluminium hydroxide, phosphorus containing compounds and halogenated compounds as a fire retardant agent.

19. (Previously Presented) A curable composition in accordance with claim 17, incorporating chlorosilane and/or aminosilane as a coupling agent.

20. (Previously Presented) A cured dielectric composition comprising the cured form of a composition in accordance with any one of claim 1.

21. (Original) An electronic circuit board comprising a conductive circuit mounted on a substrate that comprises a cured composition in accordance with claim 20.

22. (Original) An electronic circuit board in accordance with claim 21 wherein the conductive circuit comprises copper.

23. (Previously Presented) A method of manufacturing a cured composition for use as a substrate for an electronic circuit board, the method comprising continuously forming a sheet of a composition as defined in claim 1 and effecting curing of said composition.

24. (Previously Presented) A method of forming an electronic circuit comprising producing an assembly which comprises the cured form of a composition as claimed in claim 1 provided with a layer of metal on at least one surface and forming said layer or layers into a circuit.

25. (Original) A method as claimed in claim 24 wherein the assembly-is produced by: (a) forming the uncured composition into a sheet; (b) applying a metal layer to at least one surface of the sheet; and (c) effecting curing of the composition.

26. (Original) A method as claimed in claim 24 wherein the assembly is produced by: (a) forming the uncured composition into a sheet; (b) effecting curing of the composition. applying a copper layer to the cured sheet by the use of methods such as bonding films and vapour deposition.

27. (New) “A curable dielectric composition comprising polynorbornene, a polymeric diluent which plasticises the composition, a particulate material and a curing agent for the composition wherein the polymeric diluent is an ethylene propylene diene (EPDM) elastomer in which the diene group is ethylidene norbornene whereby the polymeric diluent incorporates unsaturated alkylene groups so as to be co-curable with the polynorbornene.”